

FEATURES:

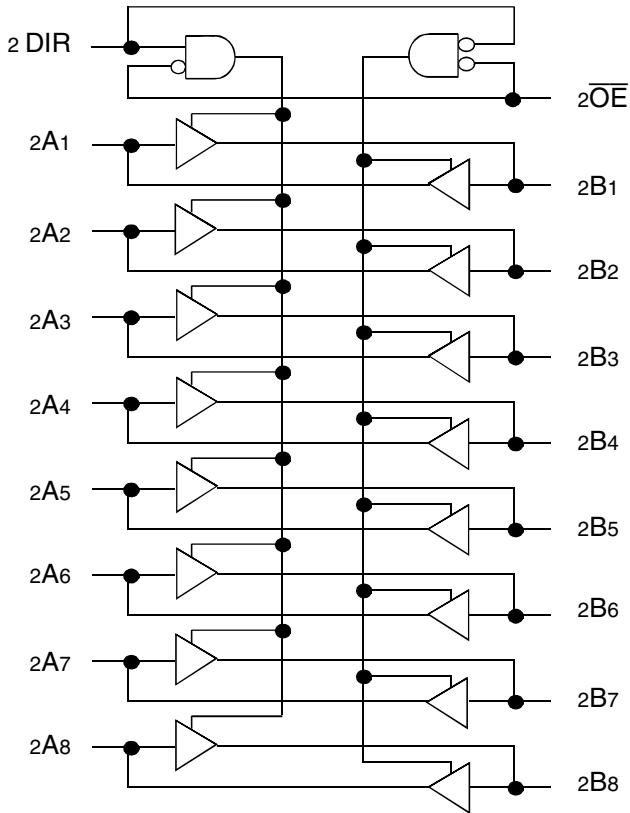
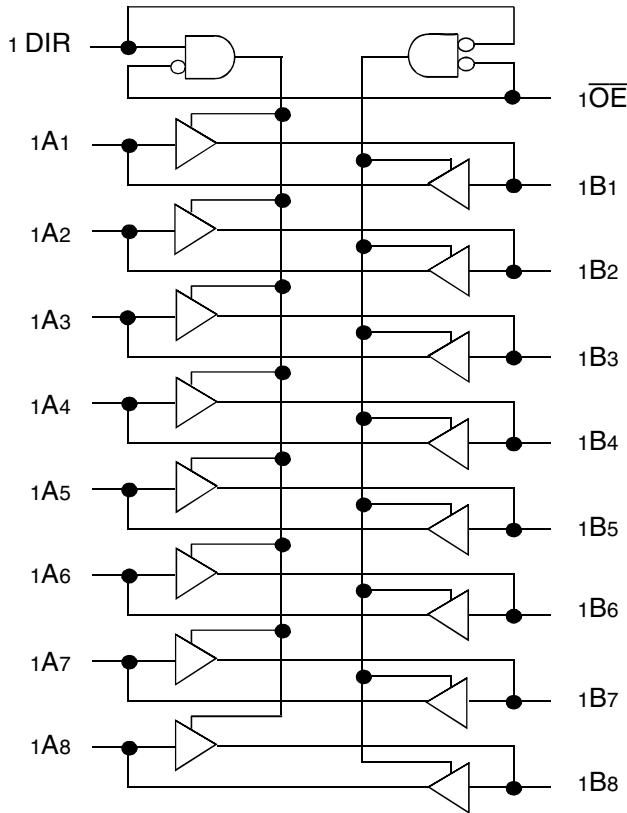
- 0.5 MICRON CMOS Technology
- High-speed, low-power CMOS replacement for ABT functions
- Typical $t_{sk(o)}$ (Output Skew) < 250ps
- Low input and output leakage $\leq 1\mu A$ (max.)
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model ($C = 200pF$, $R = 0$)
- Light drive A port: $\pm 8mA$
- High drive B port: $+64mA$, $-32mA$
- Minimal system switching noise
- Typical V_{OL} (Output Ground Bounce) < 0.25V at $V_{CC} = 5V$, $T_A = 25^\circ C$ (A port switching)
- Power off disable outputs permit "live insertion"
- Available in SSOP and TSSOP packages

DESCRIPTION:

The FCT166245T 16-bit transceiver is built using advanced dual metal CMOS technology. These high-speed, low-power transceivers are ideal for synchronous communication between two buses (A and B). The Direction and Output Enable controls operate these devices as either two independent 8-bit transceivers or one 16-bit transceiver. The direction control pin ($xDIR$) controls the direction of data flow. The output enable pin (xOE) overrides the direction control and disables both ports. All inputs are designed with hysteresis for improved noise margin.

The FCT166245T is suited for very low noise, point-to-point driving where there is a single receiver, or a light lumped load (<100pF). The buffers are designed to limit the output current to levels which will avoid noise and ringing on the signal lines without using external series terminating resistors. These parts have a $\pm 8mA$ driver on the "A" Port and a $+64/-32mA$ driver on the "B" Port, making them ideal for interfacing noisy system busses to noise sensitive interfaces.

FUNCTIONAL BLOCK DIAGRAM



PIN CONFIGURATION

1DIR		1	48	1OE
1B1		2	47	1A1
1B2		3	46	1A2
GND		4	45	GND
1B3		5	44	1A3
1B4		6	43	1A4
VCC		7	42	VCC
1B5		8	41	1A5
1B6		9	40	1A6
GND		10	39	GND
1B7		11	38	1A7
1B8		12	37	1A8
2B1		13	36	2A1
2B2		14	35	2A2
GND		15	34	GND
2B3		16	33	2A3
2B4		17	32	2A4
VCC		18	31	VCC
2B5		19	30	2A5
2B6		20	29	2A6
GND		21	28	GND
2B7		22	27	2A7
2B8		23	26	2A8
2DIR		24	25	2OE

SSOP/ TSSOP
TOP VIEWABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Description	Max	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +7	V
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to Vcc+0.5	V
TSTG	Storage Temperature	-65 to +150	°C
IOUT	DC Output Current	-60 to +120	mA

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- All device terminals except FCT162XXX and FCT166XXXT(A port) Output and I/O terminals.
- Output and I/O terminals for FCT162XXX and FCT166XXXT(A port).

CAPACITANCE ($T_A = +25^\circ\text{C}$, $F = 1.0\text{MHz}$)

Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
CIN	Input Capacitance	$V_{IN} = 0\text{V}$	3.5	6	pF
COUT	Output Capacitance	$V_{OUT} = 0\text{V}$	3.5	8	pF

NOTE:

- This parameter is measured at characterization but not tested.

PIN DESCRIPTION

Pin Names	Description
xOE	3-State Output Enable Inputs (Active LOW)
xDIR	Direction Control Input
xAx	Side A Inputs or 3-State Outputs ⁽¹⁾
xBx	Side A Inputs or 3-State Outputs ⁽²⁾

NOTES:

- This is the $\pm 8\text{mA}$ port.
- This is the $+64/-32\text{mA}$ port.

FUNCTION TABLE⁽¹⁾

Inputs		Outputs
xOE	DIR	
L	L	Bus B Data to Bus A
L	H	Bus A Data to Bus B
H	X	Z

NOTE:

- H = HIGH Voltage Level
- L = LOW Voltage Level
- X = Don't Care
- Z = High-Impedance

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial: TA = -40°C to +85°C, V_{CC} = 5.0V ±10%

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
V _{IH}	Input HIGH Level	Guaranteed Logic HIGH Level		2	—	—	V
V _{IL}	Input LOW Level	Guaranteed Logic LOW Level		—	—	0.8	V
I _{IH}	Input HIGH Current (Input pins) ⁽⁵⁾	V _{CC} = Max.	V _I = V _{CC}	—	—	±1	μA
	Input HIGH Current (I/O pins) ⁽⁵⁾			—	—	±1	
I _{IL}	Input LOW Current (Input pins) ⁽⁵⁾		V _I = GND	—	—	±1	
	Input LOW Current (I/O pins) ⁽⁵⁾			—	—	±1	
I _{OZH}	High Impedance Output Current	V _{CC} = Max.	V _O = 2.7V	—	—	±1	μA
I _{OZL}	(3-State Output pins) ⁽⁵⁾		V _O = 0.5V	—	—	±1	
V _{IK}	Clamp Diode Voltage	V _{CC} = Min., I _{IN} = -18mA		—	-0.7	-1.2	V
I _{OS}	Short Circuit Current	V _{CC} = Max., V _O = GND ⁽³⁾		-80	-140	-250	mA
V _H	Input Hysteresis	—		—	100	—	mV
I _{CCL} I _{CCH} I _{CCZ}	Quiescent Power Supply Current	V _{CC} = Max. V _{IN} = GND or V _{CC}		—	5	500	μA

OUTPUT DRIVE CHARACTERISTICS (A-PORT)

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
I _{ODL}	Output LOW Current	V _{CC} = 5V, V _{IN} = V _{IH} or V _{IL} , V _O = 1.5V ⁽³⁾		16	48	96	mA
I _{ODL}	Output HIGH Current	V _{CC} = 5V, V _{IN} = V _{IH} or V _{IL} , V _O = 1.5V ⁽³⁾		-16	-48	-96	mA
V _{OH}	Output HIGH Voltage	V _{CC} = Min. V _{IN} = V _{IH} or V _{IL}	I _{OH} = -8mA	2.4	3.3	—	V
V _{OL}	Output LOW Voltage	V _{CC} = Min. V _{IN} = V _{IH} or V _{IL}	I _{OL} = 8mA	—	0.3	0.55	V

OUTPUT DRIVE CHARACTERISTICS (B-PORT)

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
I _O	Output Drive Current	V _{CC} = Max., V _O = 2.5V ⁽³⁾		-50	—	-180	mA
V _{OH}	Output HIGH Voltage	V _{CC} = Min. V _{IN} = V _{IH} or V _{IL}	I _{OH} = -3mA	2.5	3.5	—	V
			I _{OH} = -15mA	2.4	3.5	—	
			I _{OH} = -32mA ⁽⁴⁾	2	3	—	
V _{OL}	Output LOW Voltage	V _{CC} = Min. V _{IN} = V _{IH} or V _{IL}	I _{OL} = 64mA	—	0.2	0.55	V
I _{OFF}	Input/Output Power Off Leakage	V _{CC} = 0V, V _{IN} or V _O ≤ 4.5V		—	—	±1	μA

NOTES:

1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
2. Typical values are at V_{CC} = 5.0V, +25°C ambient.
3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.
4. Duration of the condition can not exceed one second.
5. The test limit for this parameter is ±5μA at TA = -55°C.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
ΔI_{CC}	Quiescent Power Supply Current TTL Inputs HIGH	$V_{CC} = \text{Max.}$ $V_{IN} = 3.4V^{(3)}$		—	0.5	1.5	mA
I_{CCD}	Dynamic Power Supply Current ⁽⁴⁾	$V_{CC} = \text{Max.}$, Outputs Open $x\bar{OE} = xDIR = GND$ One Input Toggling 50% Duty Cycle	$V_{IN} = V_{CC}$ $V_{IN} = GND$	—	60	100	$\mu A / MHz$
I_C	Total Power Supply Current ⁽⁶⁾	$V_{CC} = \text{Max.}$, Outputs Open $f_i = 10MHz$ 50% Duty Cycle $x\bar{OE} = xDIR = GND$ One Bit Toggling	$V_{IN} = V_{CC}$ $V_{IN} = GND$	—	0.6	1.5	mA
			$V_{IN} = 3.4V$ $V_{IN} = GND$	—	0.9	2.3	
		$V_{CC} = \text{Max.}$, Outputs Open $f_i = 2.5MHz$ 50% Duty Cycle $x\bar{OE} = xDIR = GND$ Sixteen Bits Toggling	$V_{IN} = V_{CC}$ $V_{IN} = GND$	—	2.4	4.5 ⁽⁵⁾	
			$V_{IN} = 3.4V$ $V_{IN} = GND$	—	6.4	16.5 ⁽⁵⁾	

NOTES:

1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.

2. Typical values are at $V_{CC} = 5.0V$, $+25^\circ C$ ambient.

3. Per TTL driven input ($V_{IN} = 3.4V$). All other inputs at V_{CC} or GND.

4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.

5. Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.

6. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$

$$I_C = I_{CC} + \Delta I_{CC} D_{HNT} + I_{CCD} (f_{CP} N_{CP}/2 + f_i N_i)$$

I_{CC} = Quiescent Current (I_{CCL} , I_{CH} and I_{CZ})

ΔI_{CC} = Power Supply Current for a TTL High Input ($V_{IN} = 3.4V$)

D_H = Duty Cycle for TTL Inputs High

N_T = Number of TTL Inputs at D_H

I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)

f_{CP} = Clock Frequency for Register Devices (Zero for Non-Register Devices)

N_{CP} = Number of Clock Inputs at f_{CP}

f_i = Input Frequency

N_i = Number of Inputs at f_i

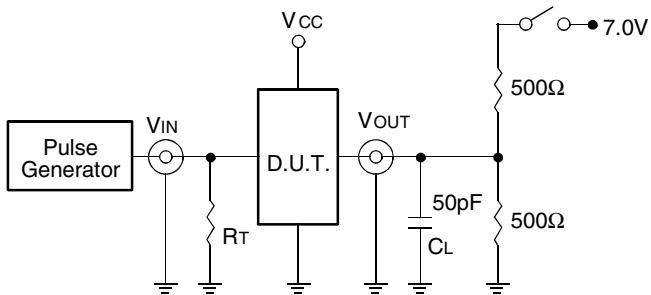
SWITCHING CHARACTERISTICS OVER OPERATING RANGE

Symbol	Parameter	Condition ⁽¹⁾	FCT166245T		FCT166245AT		Unit
			Min. ⁽²⁾	Max.	Min. ⁽²⁾	Max.	
t_{PLH}	Propagation Delay A to B	CL = 50pF RL = 500Ω	1.5	4.6	1.5	4.1	ns
t_{PHL}	Propagation Delay B to A		1.5	7	1.5	4.6	ns
t_{PZH}	Output Enable Time $x\bar{OE}$ to B		1.5	6.2	1.5	5.8	ns
t_{PZL}	Output Enable Time $x\bar{OE}$ to A		1.5	9.5	1.5	6.2	ns
t_{PHZ}	Output Disable Time $x\bar{OE}$ to B		1.5	5	1.5	4.8	ns
t_{PLZ}	Output Disable Time $x\bar{OE}$ to A		1.5	7.5	1.5	5	ns
t_{PZH}	Output Enable Time DIR to B ⁽³⁾		1.5	6.2	1.5	5.8	ns
t_{PZL}	Output Enable Time DIR to A ⁽³⁾		1.5	9.5	1.5	6.2	ns
t_{PHZ}	Output Disable Time DIR to B ⁽³⁾		1.5	5	1.5	4.8	ns
t_{PLZ}	Output Disable Time DIR to A ⁽³⁾		—	0.5	—	0.5	ns
$t_{SK(0)}$	Output Skew ⁽⁴⁾						

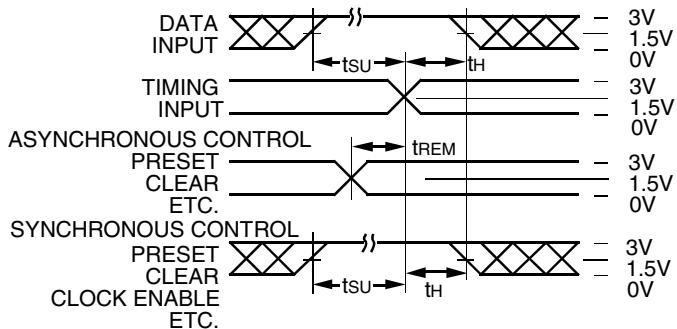
NOTES:

1. See test circuits and waveforms.
2. Minimum limits are guaranteed but not tested on Propagation Delays.
3. This parameter is guaranteed but not tested.
4. Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

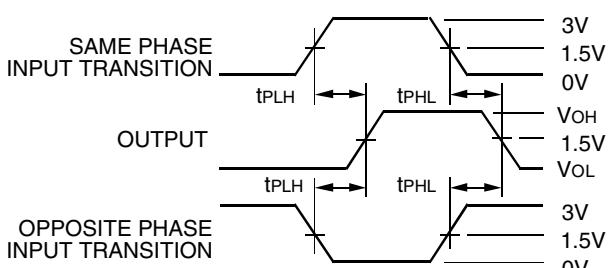
TEST CIRCUITS AND WAVEFORMS



Test Circuits for All Outputs



Set-up, Hold, and Release Times



Propagation Delay

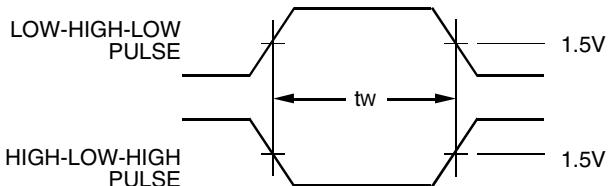
SWITCH POSITION

Test	Switch
Open Drain	Closed
Disable Low	
Enable Low	
All Other Tests	Open

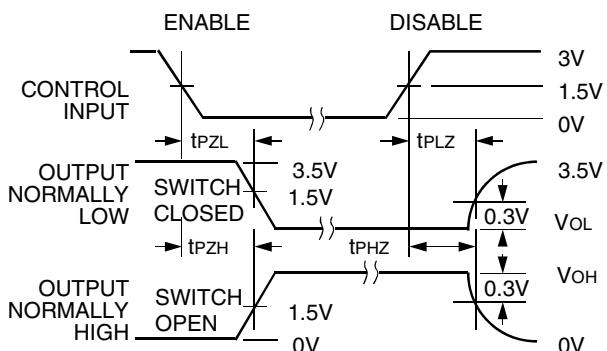
DEFINITIONS:

C_L = Load capacitance: includes jig and probe capacitance.

R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator.



Pulse Width

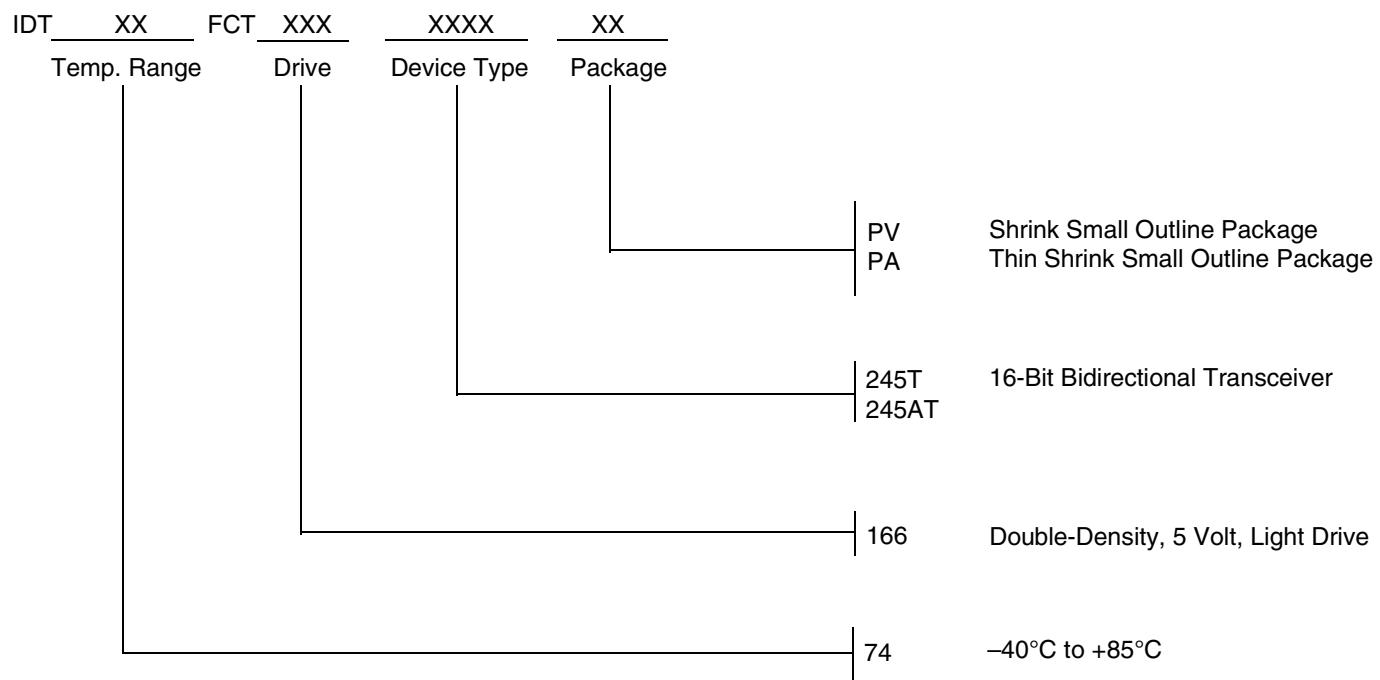


Enable and Disable Times

NOTES:

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
2. Pulse Generator for All Pulses: Rate $\leq 1.0\text{MHz}$; $t_f \leq 2.5\text{ns}$; $t_r \leq 2.5\text{ns}$.

ORDERING INFORMATION



CORPORATE HEADQUARTERS
6024 Silver Creek Valley Road
San Jose, CA 95138

for SALES:
800-345-7015 or 408-284-8200
fax: 408-284-2775
www.idt.com

for Tech Support:
logichelp@idt.com